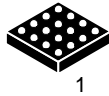


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

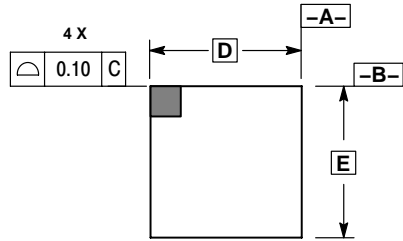
ON Semiconductor®



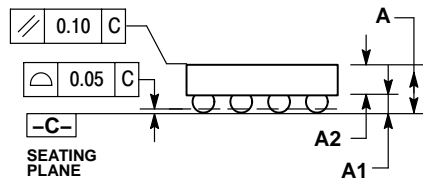
SCALE 4:1

16 PIN FLIP-CHIP
CASE 499AN-01
ISSUE O

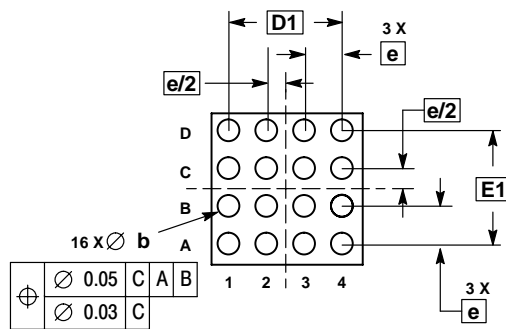
DATE 17 JUN 2005



TOP VIEW



SIDE VIEW



BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| MILLIMETERS | | |
|-------------|-----------|-------|
| DIM | MIN | MAX |
| A | --- | 0.700 |
| A1 | 0.210 | 0.270 |
| A2 | 0.380 | 0.430 |
| D | 2.000 BSC | |
| E | 2.000 BSC | |
| b | 0.290 | 0.340 |
| e | 0.500 BSC | |
| D1 | 1.500 BSC | |
| E1 | 1.500 BSC | |

| | | |
|------------------|----------------------------------|--|
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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | 16 PIN FLIP-CHIP, 2.00 X 2.00 MM | PAGE 1 OF 2 |

